

04-06-2004



To the Assistant Commissioner For

uments or copy thereof.

102713326

22553 U.S. PTO
10/812889



1. Name of conveying party(ies):
Robert Japp, Kostas Papatomas

Additional names of conveying party(ies) attached?
 Yes No

3. Nature of Conveyance
 Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: 3/30/04

2. Name and address of receiving party(ies):
Name: Endicott Interconnect Technologies, Inc.

Street Address: 1701 North Street
City: Endicott
State: New York Zip: 13760

Additional name(s) & address(es) attached?
 Yes No

3/31/04

4. Application number(s) or patent number(s):
Title DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES

If this document is being filed together with a new application, the execution date of the application is 3/30/04

A. Patent Application No(s). B. Patent No(s).

Additional numbers attached?
 Yes No

10812889

5. Name and address of party to whom correspondence concerning document should be mailed:
Lawrence R. Fraley
IP Law Counsel
Endicott Interconnect Technologies, Inc.
0099/257-4 AA12
1701 North Street, Endicott, New York 13760

6. Total number of applications and patents involved: 1

7. Total fee (37 CVF 3.41): \$40.00
 Enclosed

DO NOT USE THIS SPACE

9. Statement and signature
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley *Lawrence R. Fraley* 3/30/04
Name of Person Signing Signature Date

Registration # 26,885 Tel: 561-575-3608 Total number of pages comprising cover sheet: 2

04/05/2004 MGETACHE 00000137 10812889
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ASSIGNMENT

Whereas, we

- | | | |
|-----|------------------------------------|---|
| (1) | Robert Japp
County of Broome | City of Vestal
And State of New York |
| (2) | Kostas Papathomas
County Broome | City of Endicott
And State of New York |

have invented certain improvements in DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES

and have executed, respectively, a United States patent application therefor on

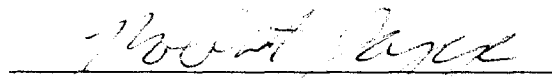
(1) *MARCH 30, 2004*, (2) *March 30 . 2004*

And whereas, ENDICOTT INTERCONNECT TECHNOLOGIES, INC., a corporation of New York, having a place of business at Endicott, New York 13760, (hereinafter called EI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

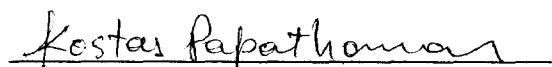
Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to EI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for protection in the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to EI, its successors and assigns; and we hereby agree that EI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by EI.

Signed:

at Endicott, New York, this 30 day of MARCH, 2004.


Robert Japp

at Endicott, New York, this 30 day of March, 2004.


Kostas Papathomas